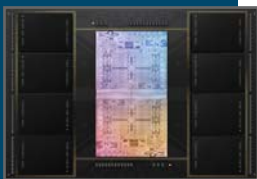
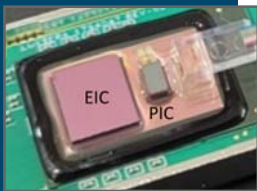
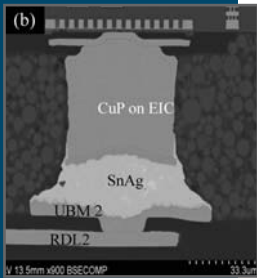
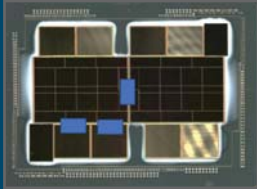


Advanced Packaging Update: Market and Technology Trends

Vol. 2-0722



This issue of the Advanced Packaging Update includes an analysis of OSAT financials, new high-performance package introductions, and trends in co-packaged optics. An updated analysis of the substrate capacity shortage is presented, along with an assessment of the financial health of the industry. TechSearch International's annual survey on substrate design rules is presented, with special coverage of suppliers of laminate flip chip BGA and CSP substrates worldwide. The design rules include body size, core thickness, via and pad diameter, minimum bump pitch supported, and substrate finish.

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